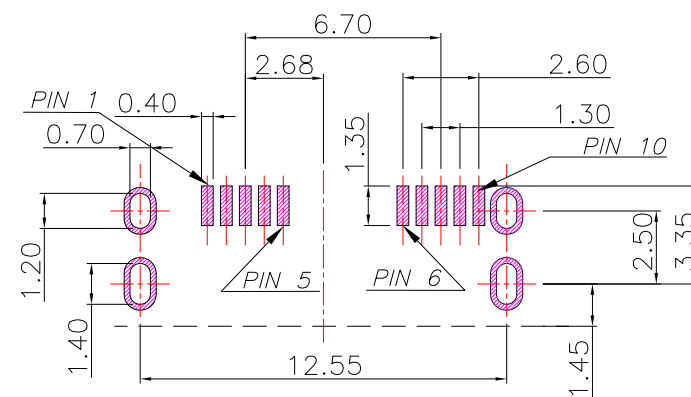
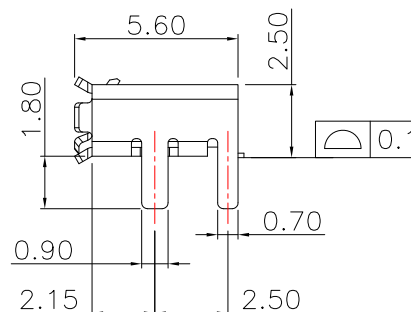
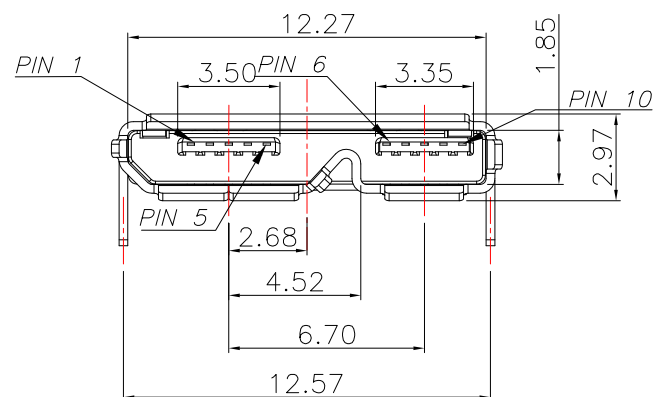
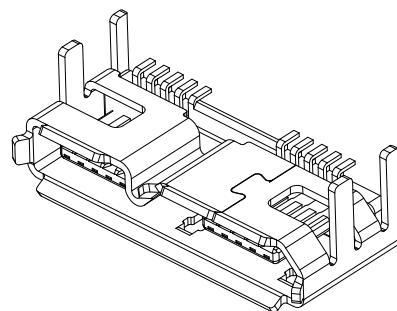
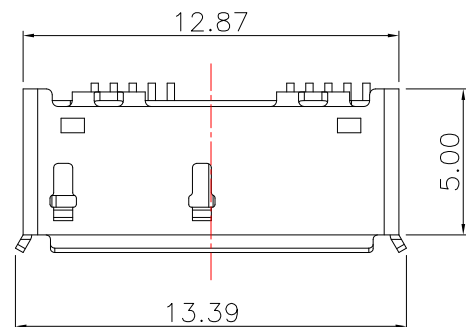




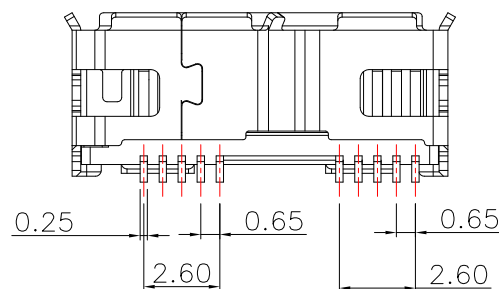
MRUSB-10B-D4-30x-S277

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"



P.C.B LAYOUT MOUNTING PATTERN



NOTE:

1.MATERIAL:

- 1.1 INSULATOR: LCP, UL 94V-0
- 1.2 CONTACT: BRASS
- 1.3 SHELL: SUS 304

2.Finish:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
TIN PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
- 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER



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CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS
OTHERWISE STATED :

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 03/13/15
DATE: 03/13/15
DATE: 03/13/15

MAT'L
FINISH
SCALE: 1 : 1
SHEET NO. 1 of 1

TITLE: CONNECTOR
MODLE: MICRO USB 3.0 B 型 母座 SMT
外殼 4腳 DIP
DWG NO. MRUSB-10B-D4-30x-S277
PART NO. MRUSB-10B-D4-30x-S277

SIZE: A4
VER: R1

ITEM NO.	DESCRIPTION	DRAWN	DATE
1	新增pin定義	Jack	031315